

Part Number: XDMYK46A

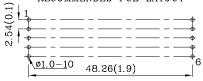
44.5mm (1.75") SINGLE DIGIT NUMERIC DIS-PLAY

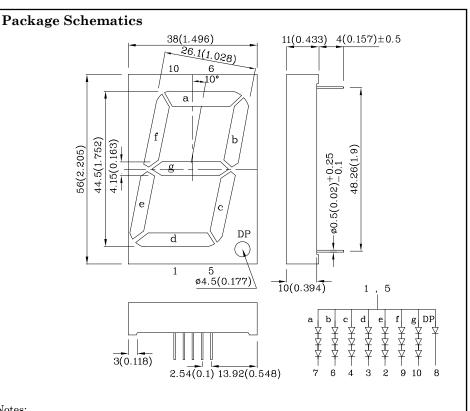
Features

- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



RECOMMENDED PCB LAYOUT







1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01")$ unless otherwise noted. 2. Specifications are subject to change without notice.

| Absolute Maximum Ratings (T _A =25°C) | | MYK (AlGaInP) | Unit | |
|--|---------------------------|------------------|------|--|
| Reverse Voltage (Per Chip) | V_{R} | 5 | V | |
| Forward Current (Dp) | I _F 30 (30) | | mA | |
| Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width (Dp) | ifs | 175 (175) | mA | |
| Power Dissipation (Per Chip) | P_{D} | 75 | mW | |
| Operating Temperature | $T_{\rm A}$ | -40 ~ +85 | •C | |
| Storage Temperature | Tstg | -40 ~ +85 | | |
| Lead Solder Temperature [2mm Below Package Base] | 260°C For 3~5 Seconds | | | |

| Operating Characteristics (T _A =25°C) | | MYK (AlGaInP) | Unit | |
|--|--------------------|------------------|------|--|
| Forward Voltage (Typ.) (Dp) (I _F =10mA) | $V_{\rm F}$ | 5.85 (1.95) | V | |
| Forward Voltage (Max.) (Dp) (I _F =10mA) | $V_{\rm F}$ | 7.5 (2.5) | V | |
| Reverse Current (Max.) (Per Chip) (V _R =5V) | I_R | 10 | uA | |
| Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA) | λP | 590* | nm | |
| Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA) | λD | 590* | nm | |
| Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA) | $	riangle \lambda$ | 20 | nm | |
| Capacitance (Typ.) (V _F =0V, f=1MHz) | С | 20 | pF | |

| Part Number | Emitting Color | Emitting Material | Luminous Intens CIE127-2007* (IF=10mA) ucc | CIE127-2007* | Description |
|----------------|-------------------|----------------------|--|--------------|------------------------------------|
| | | | min. typ | | |
| XDMYK46A | Yellow | AlGaInP | 255000 5899 88000* 1899 | 590* | Common Anode , Rt.Hand Decimal. |

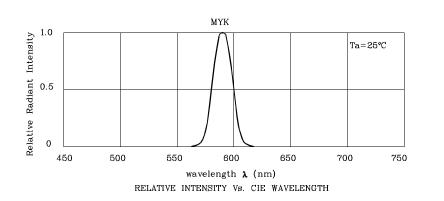
th are in accordance with CIE127-2007 standards. iminous inte and waveleng Mar 10,2014

XDSB7103 V2-X Layout: Maggie L.

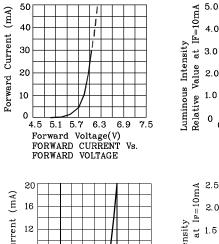


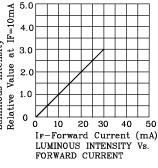
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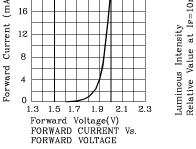
44.5mm (1.75") SINGLE DIGIT NUMERIC DIS-PLAY



✤ MYK









1.0

0.5

0

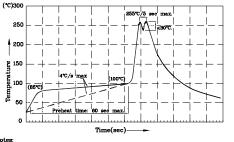
0 4 8 12 16 20

-Forward Current (mA)

Vs.

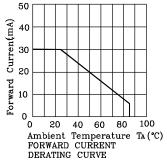
LUMINOUS INTENSITY

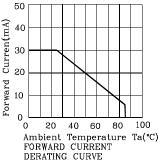
FORWARD CURRENT

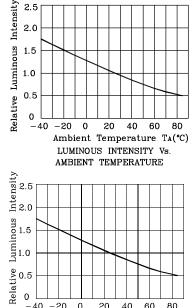


end pre-heat temperature of 105°C or less (as measured with a ouple attached to the LED pins) prior to immersion in the solder th a maximum solder bath temperature of 260°C the with a maximum solder bath temper wave soldering temperature between wave 2. Peak max). 245°C sec (5

 A.Do and apply stress to the epoxy resin while the temperature is a 4.Fixtures should not incur stress on the component when mounting during soldering process.
S.AC 305 solder alloy is recommended.
6.No more than one wave soldering pass.
7.During wave soldering, the PCB top-surface temperature should be kept below 105°C. ounting and







Ambient Temperature Ta(°C)

LUMINOUS INTENSITY Vs.

AMBIENT TEMPERATURE

Remarks:

If special sorting is required (e.g. binning based on forward voltage,

40 -20 0 20 40 60 80

luminous intensity / luminous flux, or wavelength),

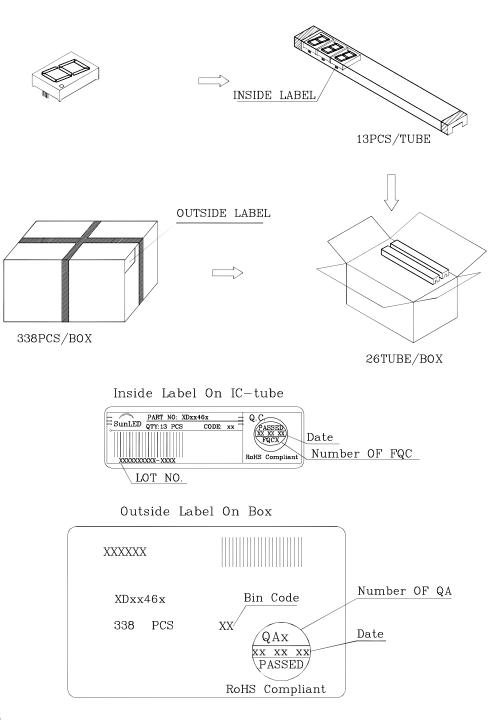
the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp